

O I P E
OCT 14 2003
PATENT & TRADEMARK OFFICE

Exhibit 1

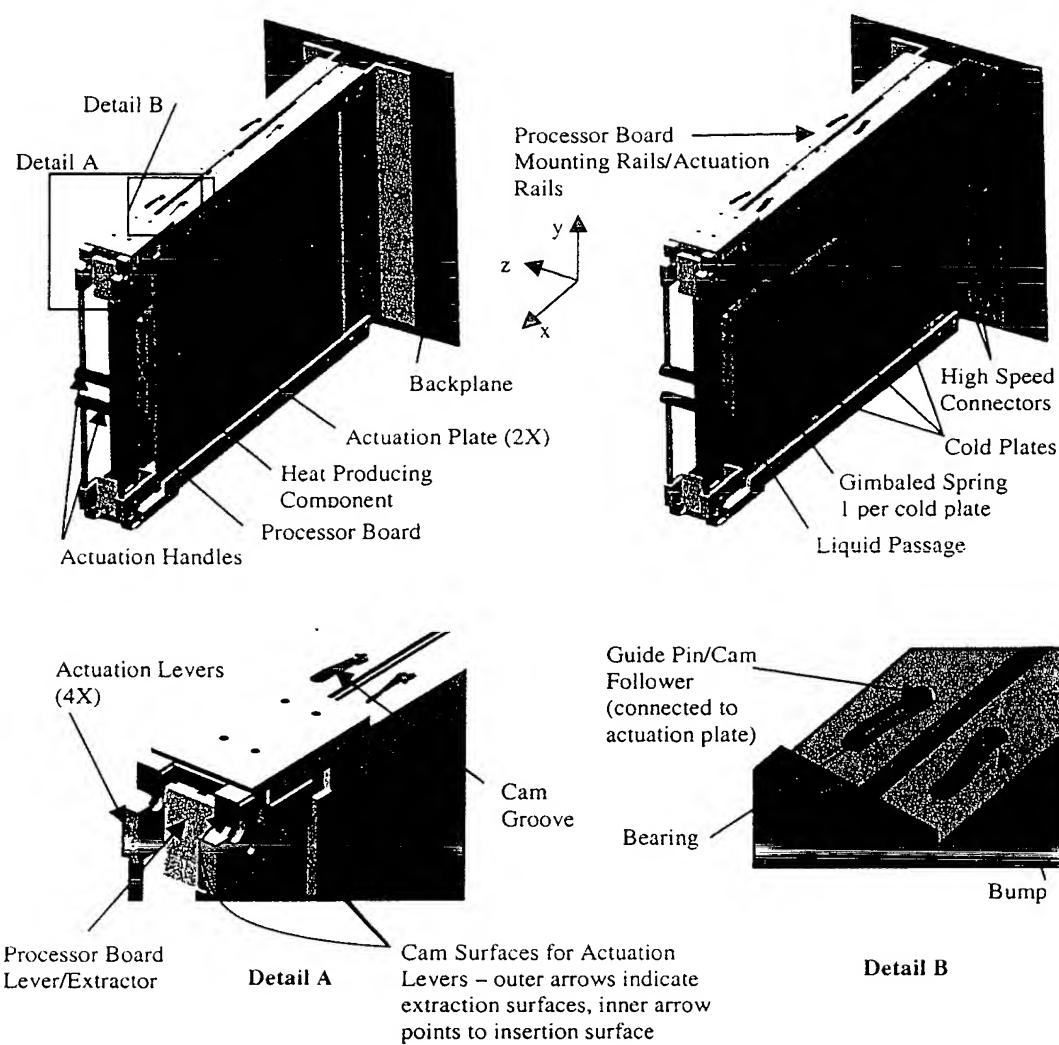


Figure 3. Mechanically Actuated Thermal Connector Assembly

6/21/00
Glen C. Smith
Catalin 6/19/00
Allen T
6/19/00



Exhibit 2



Hewlett-Packard Company
1501 Page Mill Road
Mail Stop 4U-10
Palo Alto, CA 94304-1126
www.hp.com

Lloyd E. Dakin, Jr.
PATENT ATTORNEY

650 857 2295 Tel
650 852 8063 Fax
lloyd_dakin@hp.com

December 4, 2000

James R Brueggemann
Sheppard Mullin Richter
& Hampton LLP
333 S Hope St
48th Floor
Los Angeles CA 90071

RECEIVED

OCT 22 2003

TECHNOLOGY CENTER R3700

RE: Preparation of Patent Application

↓
Redacted

HP Reference No.: 10005107.

Entitled: Mechanically Actuated Thermal Connector For Cooling Electronics
HP Required Date: February 22, 2001

Dear James:

We would like you to provide a quote of the cost for your firm to prepare a US Patent application based on the HP Invention Disclosure identified above, a copy of which is enclosed.

Redacted

Sincerely,

Lloyd E. Dakin, Jr.

Enc.: HP Invention Disclosure
RFQ
Outside Counsel Checklist

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